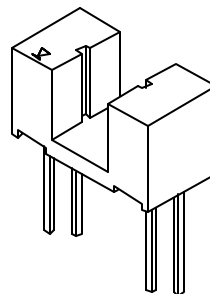
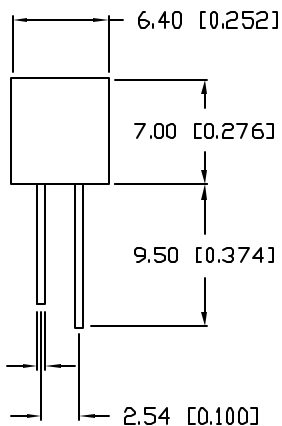
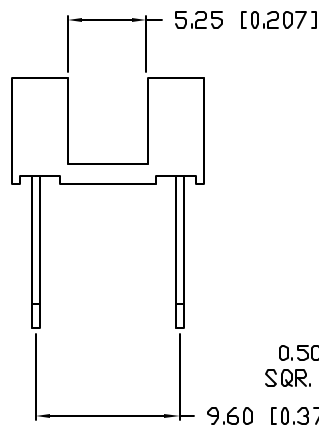
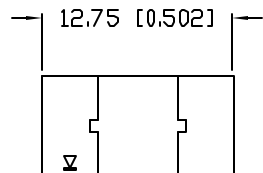


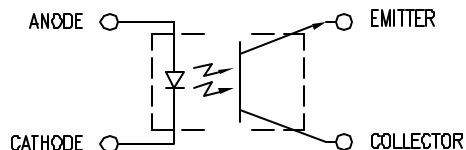
UNCONTROLLED DOCUMENT

PART NUMBER		REV.
OED-S15396		B
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN IN 3D.	5.16.03
B	E.C.N. #11148.	01.31.07



0.50 [0.020]  
SQR. (4 PLS.)

TOP VIEW PIN LAYOUT



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{ mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		940		nm	
FORWARD VOLTAGE		1.2	1.5	V	$I_f=30\text{ mA}$
REVERSE VOLTAGE	4.0			V	$I_c=10\text{ }\mu\text{A}$
DARK CURRENT			100	nA	$V_{ce}=10\text{ V}$
C/E SATURATION VOLTAGE			0.4	V	$I_c=0.5\text{ mA}$
COLLECTOR ON CURRENT		2.0		mA	$V_{ce}=5\text{ V}$
SWITCHING TIME		5		$\mu\text{S}$	$I_c=2000\text{ }\mu\text{A}$

$V_{ce}=5\text{ V}, R_I=1000\Omega$

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT	60	mA
REVERSE VOLTAGE	6	V
C/E BREAKDOWN VOLTAGE	30	V
E/C BREAKDOWN VOLTAGE	3	V
POWER DISSIPATION	725	mW
OPERATING TEMP.	-20 TO +80	$^\circ\text{C}$
STORAGE TEMP.	-25 TO +100	$^\circ\text{C}$
SOLDERING TEMP.	+250	$^\circ\text{C}$
2.0mm FROM BODY		5 SEC. MAX

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= <sup>+0.00</sup> <sub>-0.00</sub> MAX= <sup>+0.00</sup> <sub>-0.00</sub> DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
B	OED-S15396

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PHOTO INTERRUPTER.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 12.30.97
JC			PAGE: 1 OF 1
			SCALE: N/A

